

## PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT4281399

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
YOUNG HWAN JANG	02/09/2017
SIMON KAN	02/09/2017
<b>RECEIVING PARTY DATA</b>	
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<b>City:</b>	ROUND ROCK
<b>State/Country:</b>	TEXAS
<b>Postal Code:</b>	78682
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	15436727
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b> <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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<b>ATTORNEY DOCKET NUMBER:</b>	DELL-107659
<b>NAME OF SUBMITTER:</b>	HOLLI L. TEMPLETON
<b>SIGNATURE:</b>	/Holli L. Templeton/
<b>DATE SIGNED:</b>	02/17/2017
<b>Total Attachments: 2</b> source=DELL_107659_Assignment#page1.tif source=DELL_107659_Assignment#page2.tif	

# PATENT ASSIGNMENT

WHEREAS, I, Young Hwan Jang, the undersigned inventor, of Hyundai Morningside 1-cha Apt 104 dong 5, Opo-eup, Gwangju-si, Gyeonggi-do, Korea, Republic of (KR), having invented certain new and useful improvements as disclosed and/or claimed in a patent application entitled: "Improved booting of IHS from SSD using PCIE," for which application for United States Letters Patent is made, the said application having been filed concurrently herewith; and

WHEREAS, Dell Products, L.P., a Texas Limited Partnership, having a principal place of business at One Dell Way, Round Rock, TX 78682, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to Dell Products, L.P., its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to Dell Products, L.P., as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.


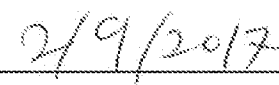
I also hereby sell and assign to Dell Products, L.P., its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to Dell Products, L.P., or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid Dell Products, L.P., its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

I authorize the later insertion of the non-provisional application number and filing date hereinbelow.

TITLE	Improved booting of IHS from SSD using PCIE		
NON-PROVISIONAL APPLICATION NO.		FILING DATE	

IN WITNESS THEREOF

 _____ Young Hwan Jang	 _____ Date
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# PATENT ASSIGNMENT

WHEREAS, I, Simon Kan, the undersigned inventor, of 88 Hillview Ave # 04-10, Hillbrooks, Singapore 669590, having invented certain new and useful improvements as disclosed and/or claimed in a patent application entitled: "Improved booting of IHS from SSD using PCIE," for which application for United States Letters Patent is made, the said application having been filed concurrently herewith; and

WHEREAS, Dell Products, L.P., a Texas Limited Partnership, having a principal place of business at One Dell Way, Round Rock, TX 78682, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to Dell Products, L.P., its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof, and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to Dell Products, L.P., as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

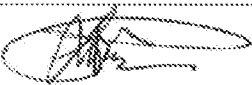
I also hereby sell and assign to Dell Products, L.P., its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

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I authorize the later insertion of the non-provisional application number and filing date hereinbelow.

TITLE	Improved booting of IHS from SSD using PCIE		
NON-PROVISIONAL APPLICATION NO.		FILING DATE	

IN WITNESS THEREOF

 Simon Kan	9 Feb 2017 Date
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